

N-Channel Enhancement Mode Field Effect Transistor

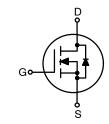
2N7000, 2N7002, NDS7002A

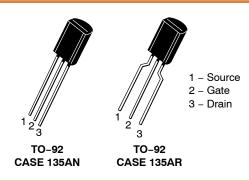
Description

These N-channel enhancement mode field effect transistors are produced using **onsemi**'s proprietary, high cell density, DMOS technology. These products have been designed to minimize on-state resistance while providing rugged, reliable, and fast switching performance. They can be used in most applications requiring up to 400 mAdc and can deliver pulsed currents up to 2 A. These products are particularly suited for low-voltage, low-current applications, such as small servo motor control, power MOSFET gate drivers, and other switching applications.

Features

- High Density Cell Design for Low R_{DS(on)}
- Voltage Controlled Small Signal Switch
- Rugged and Reliable
- High Saturation Current Capability
- This Device is Pb-Free and Halogen Free





MARKING DIAGRAM



\$Y = **onsemi** Logo &Z = Assembly Plant Code

&3 = Date Code

2N7000 = Specific Device Code



2 ° (3

1 - Gate

2 – Source 3 – Drain

MARKING DIAGRAM

CASE 318-08



702 = Specific Device Code

M = Date Code

= Pb-Free Package

(Note: Microdot may be in either location)

ORDERING INFORMATION

See detailed ordering and shipping information on page 7 of this data sheet.

ABSOLUTE MAXIMUM RATINGS Values are at T_C = 25°C unless otherwise noted.

		Value			
Symbol	Parameter	2N7000	2N7002	NDS7002A	Unit
V _{DSS}	Drain-to-Source Voltage		60		V
V _{DGR}	Drain-Gate Voltage (R _{GS} ≤ 1 MW)		60		V
V _{GSS}	Gate-Source Voltage - Continuous	±20			V
	Gate-Source Voltage - Non Repetitive (tp < 50 ms)	±40			
I _D	Maximum Drain Current - Continuous	200	115	280	mA
	Maximum Drain Current - Pulsed	500	800	1500	
P _D	Maximum Power Dissipation Derated above 25°C	400	200	300	mW
		3.2	1.6	2.4	mW/°C
T _J , T _{STG}	Operating and Storage Temperature Range	-55 to 150 -65 to 150		-65 to 150	°C
TL	Maximum Lead Temperature for Soldering Purposes, 1/16-inch from Case for 10 s	300			°C

Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.

THERMAL CHARACTERISTICS Values are at $T_C = 25$ °C unless otherwise noted.

		Value			
Symbol	Parameter	2N7000	2N7002	NDS7002A	Unit
$R_{ heta JA}$	Thermal Resistance, Junction to Ambient	312.5	625	417	°C/W

ELECTRICAL CHARACTERISTICS

Values are at T_C = 25°C unless otherwise noted.

Symbol	Parameter	Conditions	Туре	Min	Тур	Max	Unit
FF CHARA	CTERISTICS						
BV _{DSS}	Drain-Source Breakdown Voltage	V _{GS} = 0 V, I _D = 10 μA	All	60	-	-	٧
I _{DSS}	Zero Gate Voltage Drain	V _{DS} = 48 V, V _{GS} = 0 V	2N7000	-	-	1	μΑ
	Current	V _{DS} = 48 V, V _{GS} = 0 V, T _C = 125°C		-	-	1	mA
		V _{DS} = 60 V, V _{GS} = 0 V	2N7002	-	-	1	μΑ
		$V_{DS} = 60 \text{ V}, V_{GS} = 0 \text{ V},$ $T_C = 125^{\circ}\text{C}$	NDS7002A	-	-	0.5	mA
I _{GSSF}	Gate – Body Leakage,	V _{GS} = 15 V, V _{DS} = 0 V	2N7000	-	-	10	nA
	Forward	V _{GS} = 20 V, V _{DS} = 0 V	2N7002 NDS7002A	-	-	100	
I _{GSSR}	Gate – Body Leakage,	$V_{GS} = -15 \text{ V}, V_{DS} = 0 \text{ V}$	2N7000	-	-	-10	nA
	Reverse	$V_{GS} = -20 \text{ V}, V_{DS} = 0 \text{ V}$	2N7002 NDS7002A	-	-	-100	
N CHARAC	CTERISTICS		-				-
V _{GS(th)}	Gate Threshold Voltage	$V_{DS} = V_{GS}$, $I_D = 1 \text{ mA}$	2N7000	0.8	2.1	3	V
		$V_{DS} = V_{GS}$, $I_D = 250 \mu A$	2N7002 NDS7002A	1	2.1	2.5	

ELECTRICAL CHARACTERISTICS (continued)

Values are at $T_C = 25^{\circ}C$ unless otherwise noted.

Symbol	Parameter	Conditions	Туре	Min	Тур	Max	Unit
ON CHARAC	CTERISTICS						
R _{DS(on)}	Static Drain-Source	V _{GS} = 10 V, I _D = 500 mA	2N7000	-	1.2	5	Ω
	On-Resistance	$V_{GS} = 10 \text{ V}, I_D = 500 \text{ mA},$ $T_C = 125^{\circ}\text{C}$		-	1.9	9	
		V _{GS} = 4.5 V, I _D = 75 mA		-	1.8	5.3	
		V _{GS} = 10 V, I _D = 500 mA	2N7002	-	1.2	7.5	
		$V_{GS} = 10 \text{ V}, I_D = 500 \text{ mA}, T_C = 100^{\circ}\text{C}$		-	1.7	13.5	
		V _{GS} = 5 V, I _D = 50 mA		-	1.7	7.5	
		$V_{GS} = 5 \text{ V, I}_{D} = 50 \text{ mA,}$ $T_{C} = 100^{\circ}\text{C}$]	-	2.4	13.5	
		V _{GS} = 10 V, I _D = 500 mA	NDS7002A	_	1.2	2	
		$V_{GS} = 10 \text{ V}, I_D = 500 \text{ mA},$ $T_C = 125^{\circ}\text{C}$		-	2	3.5	
		$V_{GS} = 5 \text{ V}, I_D = 50 \text{ mA}$		_	1.7	3	
		V _{GS} = 5 V, I _D = 50 mA, T _C = 125°C		-	2.8	5	
V _{DS(on)}	Drain-Source On-Voltage	V _{GS} = 10 V, I _D = 500 mA	2N7000	_	0.6	2.5	V
		$V_{GS} = 4.5 \text{ V}, I_D = 75 \text{ mA}$		_	0.14	0.4	
		V _{GS} = 10 V, I _D = 500 mA	2N7002	_	0.6	3.75	
		$V_{GS} = 5.0 \text{ V}, I_D = 50 \text{ mA}$		_	0.09	1.5	
		V _{GS} = 10 V, I _D = 500 mA	NDS7002A	_	0.6	1	
		$V_{GS} = 5.0 \text{ V}, I_D = 50 \text{ mA}$		_	0.09	0.15	
I _{D(on)}	On-State Drain Current	V _{GS} = 4.5 V, V _{DS} = 10 V	2N7000	75	600	-	mA
		V_{GS} = 10 V, $V_{DS} \ge 2 V_{DS(on)}$	2N7002	500	2700	-	
		V_{GS} = 10 V, $V_{DS} \ge 2 V_{DS(on)}$	NDS7002A	500	2700	-	
9FS	Forward Transconductance	$V_{DS} = 10 \text{ V}, I_{D} = 200 \text{ mA}$	2N7000	100	320	-	mS
		$V_{DS} \ge 2 V_{DS(on)}, I_D = 200 \text{ mA}$	2N7002	80	320	-	
		$V_{DS} \ge 2 V_{DS(on)}, I_D = 200 \text{ mA}$	NDS7002A	80	320	-	
YNAMIC CI	HARACTERISTICS						
C _{iss}	Input Capacitance	V _{DS} = 25 V, V _{GS} = 0 V, f = 1.0 MHz	All	-	20	50	pF
C _{oss}	Output Capacitance	T = 1.0 WINZ	All	-	11	25	
C _{rss}	Reverse Transfer Capacitance		All	-	4	5	
t _{on}	Turn-On Time	$\begin{aligned} &V_{DD} = 15 \text{ V, R}_L = 25 \ \Omega, \\ &I_D = 500 \text{ mA, V}_{GS} = 10 \text{ V,} \\ &R_{GEN} = 25 \ \Omega \end{aligned}$	2N7000	-	_	10	ns
		$\begin{split} &V_{DD}=30 \text{ V, R}_{L}=150 \Omega,\\ &I_{D}=200 \text{ mA, V}_{GS}=10 \text{ V,}\\ &R_{GEN}=25 \Omega \end{split}$	2N7002 NDS7002A	-	_	20	
t _{off}	Turn-Off Time	V_{DD} = 15 V, R_{L} = 25 Ω , I_{D} = 500 mA, V_{GS} = 10 V, R_{GEN} = 25 Ω	2N7000	-	_	10	ns
		$\begin{aligned} &V_{DD} = 30 \text{ V, R}_L = 150 \ \Omega, \\ &I_D = 200 \text{ mA, V}_{GS} = 10 \text{ V,} \\ &R_{GEN} = 25 \ \Omega \end{aligned}$	2N7002 NDS7002A	-	_	20	

ELECTRICAL CHARACTERISTICS (continued)

Values are at $T_C = 25^{\circ}C$ unless otherwise noted.

Symbol	Parameter	Conditions	Туре	Min	Тур	Max	Unit			
DRAIN-SOU	DRAIN-SOURCE DIODE CHARACTERISTICS AND MAXIMUM RATINGS									
I _S	I _S Maximum Continuous Drain-Source Diode Forward Current			-	_	115	mA			
			NDS7002A	_	_	280				
I _{SM}	Maximum Pulsed Drain-Source Diode Forward Current		2N7002	_	-	0.8	Α			
			NDS7002A	_	_	1.5				
V _{SD}	Drain-Source Diode Forward Voltage	V _{GS} = 0 V, I _S = 115 mA (Note 1)	2N7002	-	0.88	1.5	V			
		V _{GS} = 0 V, I _S = 400 mA (Note 1)	NDS7002A	ı	0.88	1.2				

Product parametric performance is indicated in the Electrical Characteristics for the listed test conditions, unless otherwise noted. Product performance may not be indicated by the Electrical Characteristics if operated under different conditions.

TYPICAL PERFORMANCE CHARACTERISTICS

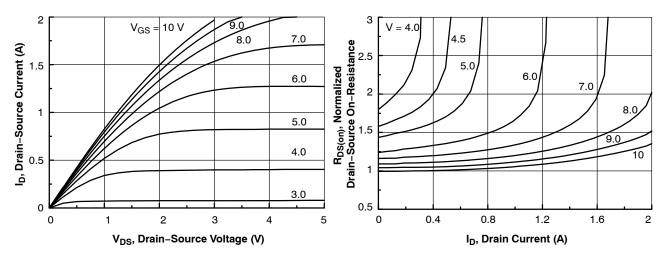


Figure 1. On-Region Characteristics

Figure 2. On–Resistance Variation with Gate Voltage and Drain Current

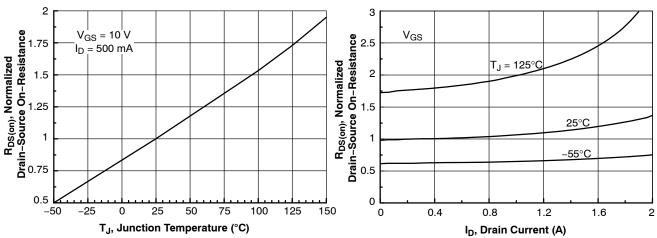


Figure 3. On–Resistance Variation with Temperature

Figure 4. On-Resistance Variation with Drain Current and Temperature

^{1.} Pulse test: Pulse Width ≤ 300 μs, Duty Cycel ≤ 2 %

TYPICAL PERFORMANCE CHARACTERISTICS (Continued)

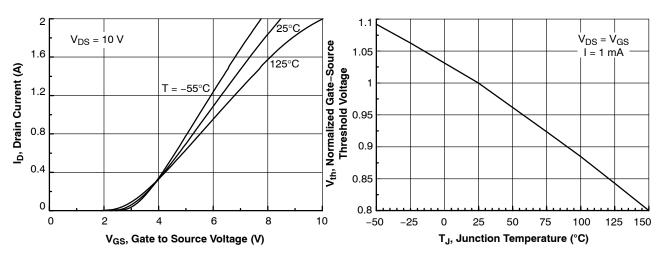


Figure 5. Transfer Characteristics

Figure 6. Gate Threshold Variation with Temperature

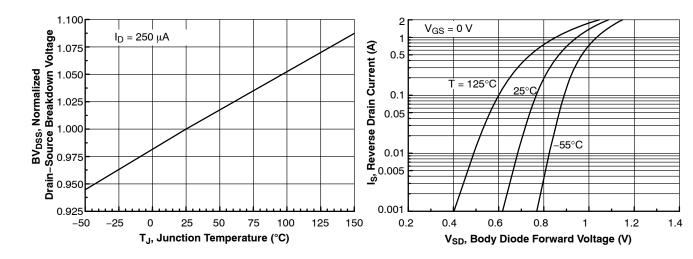


Figure 7. Breakdown Voltage Variation with Temperature

Figure 8. Body Diode Forward Voltage Variation with

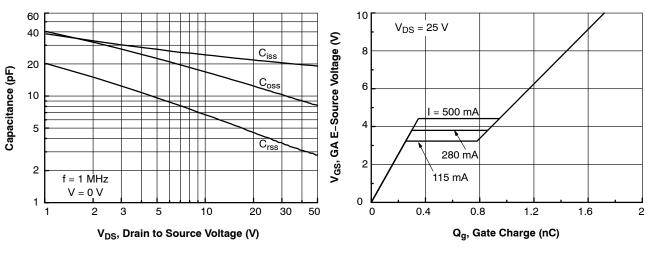


Figure 9. Capacitance Characteristics

Figure 10. Gate Charge Characteristics

TYPICAL PERFORMANCE CHARACTERISTICS (Continued)

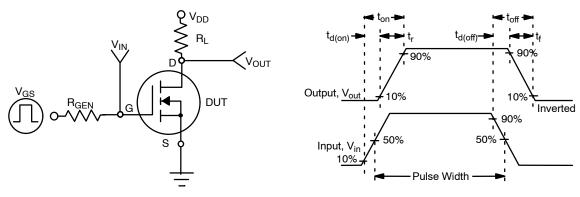


Figure 11. Switching Test Circuit

Figure 12. Switching Waveforms

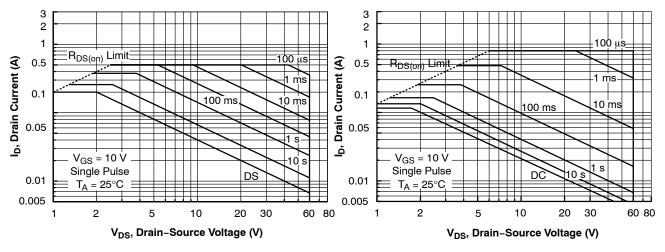


Figure 13. 2N7000 Maximum Safe Operating Area

Figure 14. 2N7002 Maximum Safe Operating Area

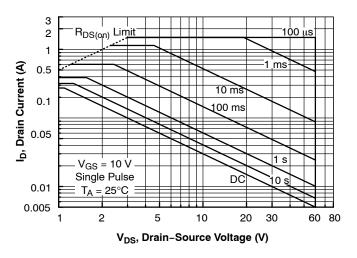


Figure 15. NDS7000A Maximum Safe Operating Area

TYPICAL PERFORMANCE CHARACTERISTICS (Continued)

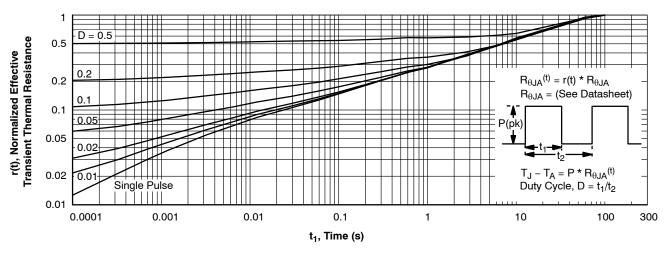


Figure 16. TO-92, 2N7000 Transient Thermal Response Curve

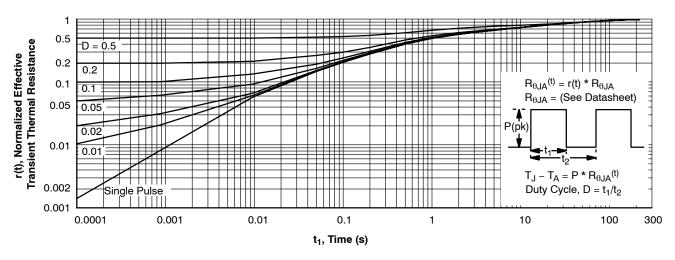


Figure 17. SOT-23, 2N7002 / NDS7002A Transient Thermal Response Curve

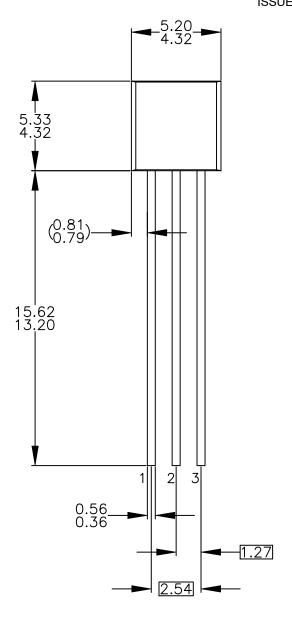
ORDERING INFORMATION

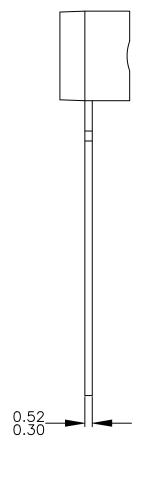
Part Number	Marking	Package	Packing Method [†]	Min Order Qty / Immediate Pack Qty
2N7000	2N7000	TO-92 3L (Pb-Free)	Bulk	10000 / 1000
2N7000-D74Z			Ammo	2000 / 2000
2N7000-D75Z			Tape and Reel	2000 / 2000
2N7000-D26Z				2000 / 2000
2N7002	702	SOT-23 3L	Tape and Reel	3000 / 3000
NDS7002A	712	(Pb-Free)		3000 / 3000

[†]For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

TO-92 3 4.825x4.76 CASE 135AN ISSUE O

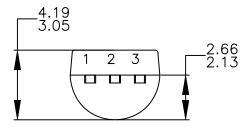
DATE 31 JUL 2016





NOTES: UNLESS OTHERWISE SPECIFIED

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- ALL DIMENSIONS ARE IN MILLIMETERS.
 DRAWING CONFORMS TO ASME Y14.5M—2009.



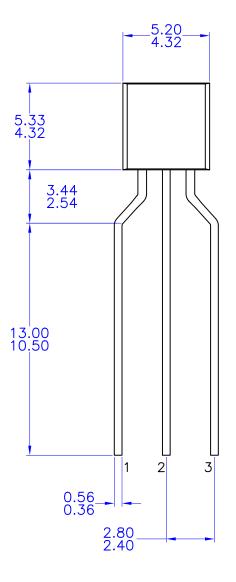
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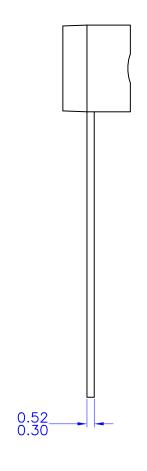
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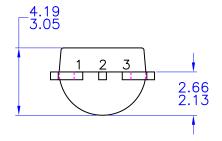
DATE 30 SEP 2016





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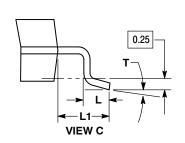


SOT-23 (TO-236) CASE 318-08 **ISSUE AS**

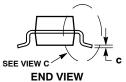
DATE 30 JAN 2018

SCALE 4:1 D - 3X b

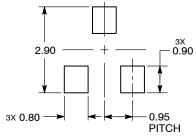
TOP VIEW







RECOMMENDED SOLDERING FOOTPRINT



DIMENSIONS: MILLIMETERS

3. ANODE

NOTES:

- NOTES:
 1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
 2. CONTROLLING DIMENSION: MILLIMETERS.
 3. MAXIMUM LEAD THICKNESS INCLUDES LEAD FINISH.
 MINIMUM LEAD THICKNESS IS THE MINIMUM THICKNESS OF THE BASE MATERIAL
- 4. DIMENSIONS D AND E DO NOT INCLUDE MOLD FLASH, PROTRUSIONS, OR GATE BURRS.

	MILLIMETERS				INCHES	
DIM	MIN	NOM	MAX	MIN	NOM	MAX
Α	0.89	1.00	1.11	0.035	0.039	0.044
A1	0.01	0.06	0.10	0.000	0.002	0.004
b	0.37	0.44	0.50	0.015	0.017	0.020
С	0.08	0.14	0.20	0.003	0.006	0.008
D	2.80	2.90	3.04	0.110	0.114	0.120
E	1.20	1.30	1.40	0.047	0.051	0.055
е	1.78	1.90	2.04	0.070	0.075	0.080
L	0.30	0.43	0.55	0.012	0.017	0.022
L1	0.35	0.54	0.69	0.014	0.021	0.027
HE	2.10	2.40	2.64	0.083	0.094	0.104
Т	O٥		100	O٥		10°

GENERIC MARKING DIAGRAM*



XXX = Specific Device Code

= Date Code

= Pb-Free Package

*This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G" or microdot " ■", may or may not be present.

STYLE 1 THRU 5: CANCELLED	STYLE 6: PIN 1. BASE 2. EMITTER 3. COLLECTOR	STYLE 7: PIN 1. EMITTER 2. BASE 3. COLLECTOR	STYLE 8: PIN 1. ANODE 2. NO CONNECTION 3. CATHODE		
STYLE 9:	STYLE 10:	STYLE 11:	STYLE 12:	STYLE 13:	STYLE 14:
PIN 1. ANODE	PIN 1. DRAIN	PIN 1. ANODE	PIN 1. CATHODE	PIN 1. SOURCE	PIN 1. CATHODE
2. ANODE	2. SOURCE	2. CATHODE	2. CATHODE	2. DRAIN	2. GATE
3. CATHODE	3. GATE	3. CATHODE-ANODE	3. ANODE	3. GATE	3. ANODE
STYLE 15:	STYLE 16:	STYLE 17:	STYLE 18:	STYLE 19:	STYLE 20:
PIN 1. GATE	PIN 1. ANODE	PIN 1. NO CONNECTION	PIN 1. NO CONNECTION	PIN 1. CATHODE	PIN 1. CATHODE
2. CATHODE	2. CATHODE	2. ANODE	2. CATHODE	2. ANODE	2. ANODE
3. ANODE	3. CATHODE	3. CATHODE	3. ANODE	3. CATHODE-ANODE	3. GATE
STYLE 21:	STYLE 22:	STYLE 23:	STYLE 24:	STYLE 25:	STYLE 26:
PIN 1. GATE	PIN 1. RETURN	PIN 1. ANODE	PIN 1. GATE	PIN 1. ANODE	PIN 1. CATHODE
2. SOURCE	2. OUTPUT	2. ANODE	2. DRAIN	2. CATHODE	2. ANODE
3. DRAIN	3. INPUT	3. CATHODE	3. SOURCE	3. GATE	3. NO CONNECTION
STYLE 27: PIN 1. CATHODE 2. CATHODE	STYLE 28: PIN 1. ANODE 2. ANODE				

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2N7000G 2N7000RLRA 2N7000RLRAG 2N7000RLRMG 2N7000RLRPG 2N7002_D87Z 2N7000BU 2N7000TA
2N7000_D75Z 2N7002 2N7002MTF NDS7002A 2N7000 2N7000_D74Z 2N7000_D26Z 2N7000_J61Z

NDS7002A_D87Z 2N7002_S00Z NDS7002A_NB9GGTXA 2N7002_NB9G002 2N7002_L99Z 2N7002_Q 2N7000_Q

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